REMARKS

Claim 1 has been amended to clearly state that the slow cure adhesive bonds overlying

surfaces together and forms a cellular structure on the collector. This is not taught or suggested

by any of the references cited in the search report. Only United States Patent No. 5,002,628

was cited against claim 1. That patent discloses a process in which an adhesive is solidified on

tubular material before that material is wound on a collector. The stacked layer is cut from the

collector and placed in stacking trays for inspection. Since the layers are not bonded together

"the flaws 154, 156 can be readily removed during this restacking and inspection

arrangement." Then the trays "are introduced to a heating and curing apparatus" where the

layers are bonded together. Col. 9, line 18 - Col. 10, line 19. No bonding of overlapping

surfaces occurs on the collector.

Claims 9-14 are directed to an apparatus for forming a cellular structure having a glue

applicator which has a reservoir filled with a slow cure adhesive. The use of a slow cure

adhesive is not taught or suggested by the prior art.

For the foregoing reasons, the claims as amended are patentable over the cited

references.

Respectfully submitted,

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